

FPC/FFCについて

打ち抜き方向は導体側から補強板側を推奨致します。
 導体部については軟烙銅35µmまたは50µmを推奨致します。
 接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。
 FPC/FFCに規定された定格温度がFPC/FFC単体前提である場合が御座います。
 コネクタと組み合わせたの実使用において、接着層が劣化する等の信頼性を満足できないケースを回避する為、
 実機での評価/確認をお願い致します。

ABOUT FPC/FFC

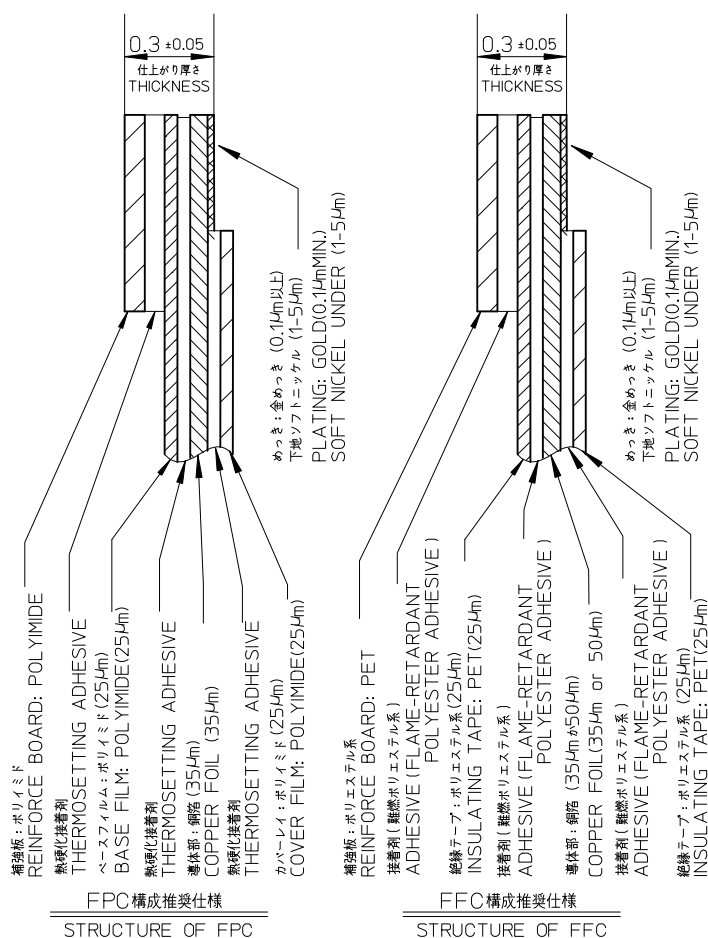
RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE
 RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL
 RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY THE HEAT RESISTANCE OF FFC IS ONLY FFC SPEC
 TO PREVENT THE CASE THAT RELIABILITY CANNOT BE SATISFIED (THE ADHESIVE IS DETERIORATED etc.) PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH ACTUAL CONNECTER

FPCについて

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25µmを推奨します。
 接着剤は熱硬化接着剤を推奨します。

ABOUT FPC

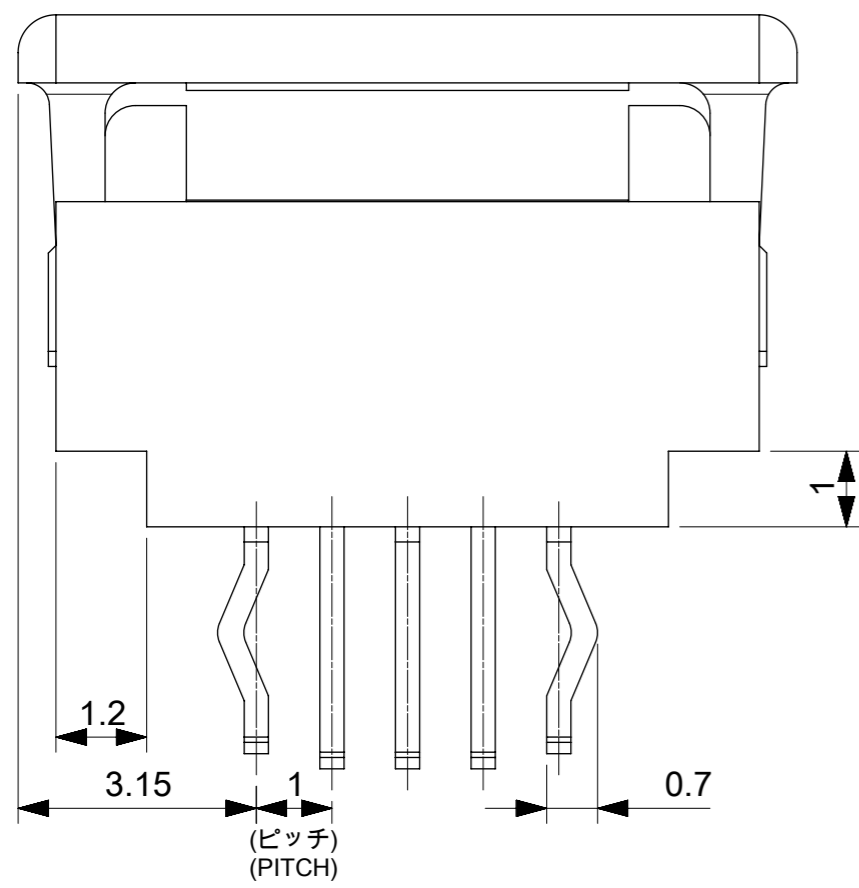
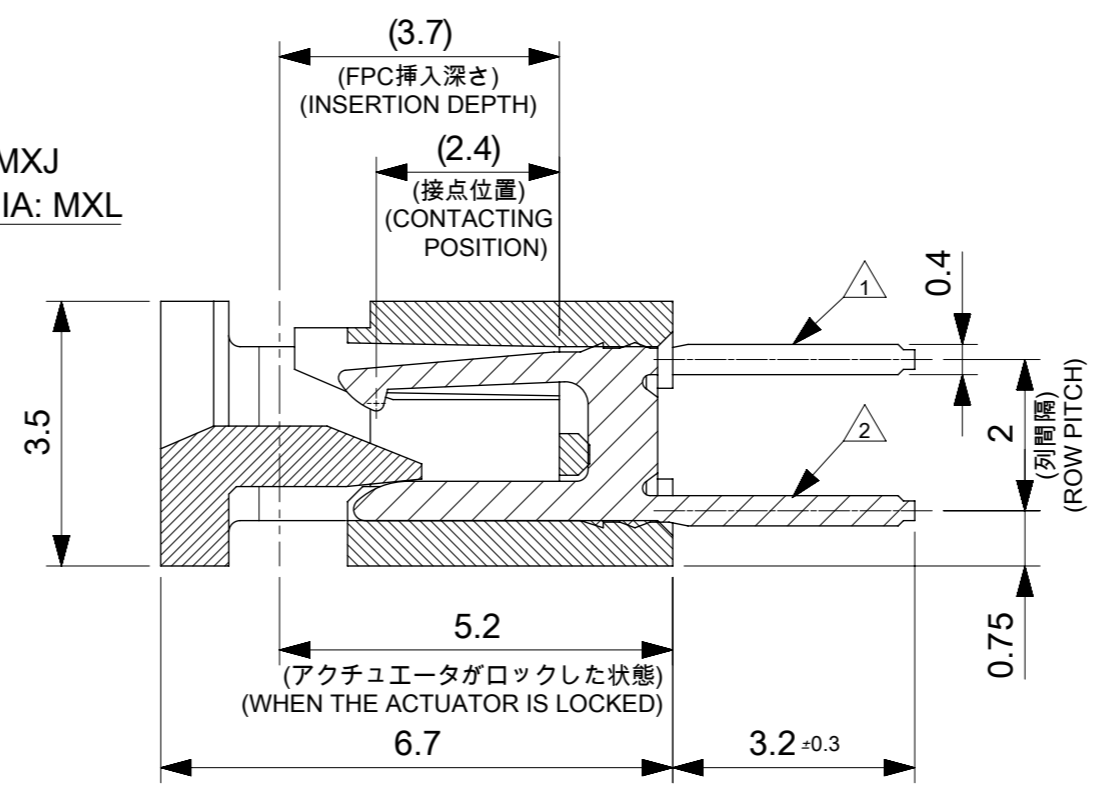
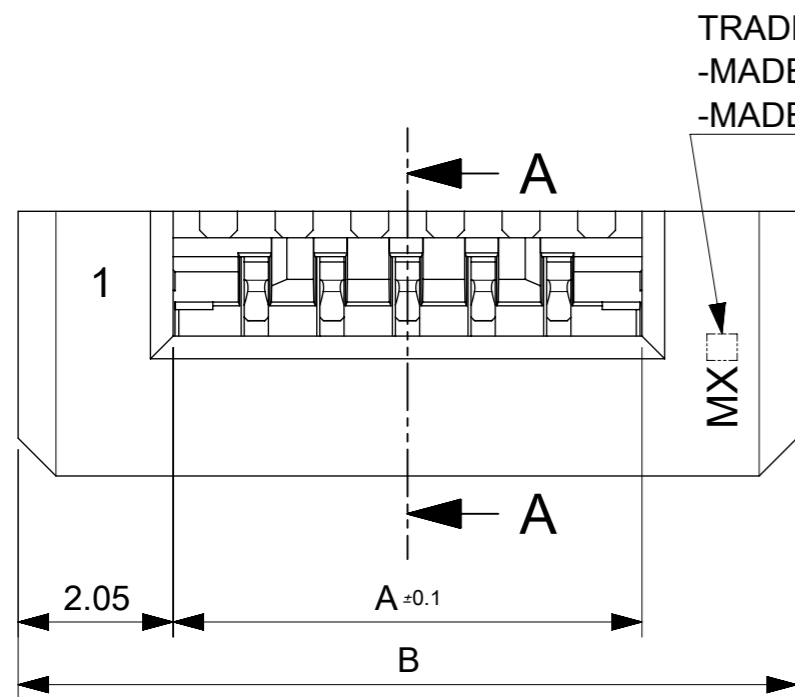
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE



FPC構成推奨仕様
 STRUCTURE OF FPC

FFC構成推奨仕様
 STRUCTURE OF FFC

REVISED EC NO: J2016-04.04 DRWN: NKONDO 2015/10/20 CHKD: KTAKAHASHI 2015/10/20 APPR: YNOGAWA 2015/10/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	MODEL NO.	52030-**75
	0.25 UNDER	UNDER	±0.2	MM ONLY		10:1	METRIC	THIRD ANGLE PROJECTION
	0.25 OVER	0.5 UNDER	±0.2	DRAWN BY	DATE	TITLE		
	0.5 OVER	1.0 UNDER	±0.2	NKONDO	2015/10/20	1.0 FPC CONN ZIF ST		
	1.0 OVER	10 UNDER	±0.2	CHECKED BY	DATE	-LEAD FREE- molex		
10 OVER	30 UNDER	±0.25	KTAKAHASHI	2015/10/20				
30 OVER		±0.3	APPROVED BY	DATE	MATERIAL NO.		DOCUMENT NO.	SHEET NO.
ANGULAR	±3 °		YNOGAWA	2015/10/21	SEE SHEET 1		SD-52030-019	2 OF 2
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
A								



注記
NOTES

- △1 CKT.NO.1を基準に偶数番目のソルダーテール。
EVEN NO. SOLDER TAIL.
- △2 CKT.NO.1を基準に奇数番目のソルダーテール。
ODD NO. SOLDER TAIL.

3. 材料

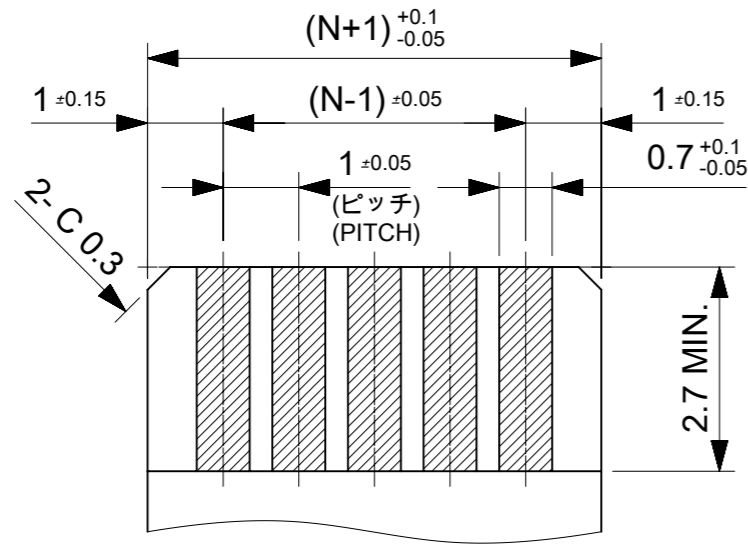
MATERIAL

ターミナル:リン青銅、ニッケル下地、錫ビスマスめっき (t=0.32)
 TERMINAL:PHOSPHOR BRONZE, TIN-BISMUTH OVER NICKEL PLATING.
 ハウジング:66ナイロン、UL94V-0
 HOUSING:66NYLON, UL94V-0
 アクチュエータ:ポリエステル、UL94V-0
 ACTUATOR:POLYESTER, UL94V-0

- 4. 本製品は、52030-**10の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52030-**10.

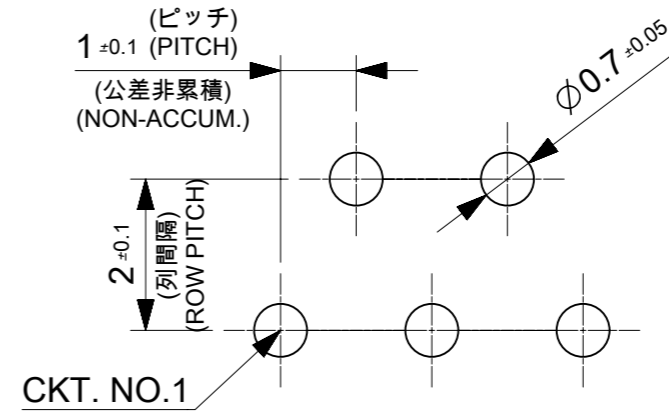
35.3	31.2	52030-3029	30
34.3	30.2	52030-2929	29
33.3	29.2	52030-2829	28
32.3	28.2	52030-2729	27
31.3	27.2	52030-2629	26
30.3	26.2	52030-2529	25
29.3	25.2	52030-2429	24
28.3	24.2	52030-2329	23
27.3	23.2	52030-2229	22
26.3	22.2	52030-2129	21
25.3	21.2	52030-2029	20
24.3	20.2	52030-1929	19
23.3	19.2	52030-1829	18
22.3	18.2	52030-1729	17
21.3	17.2	52030-1629	16
20.3	16.2	52030-1529	15
19.3	15.2	52030-1429	14
18.3	14.2	52030-1329	13
17.3	13.2	52030-1229	12
16.3	12.2	52030-1129	11
15.3	11.2	52030-1029	10
14.3	10.2	52030-0929	9
13.3	9.2	52030-0829	8
12.3	8.2	52030-0729	7
11.3	7.2	52030-0629	6
10.3	6.2	52030-0529	5
9.3	5.2	52030-0429	4
8.3	4.2	52030-0329	3
B	A	オーダー番号 ORDER NO.	極数 CKT.

QUALITY SYMBOLS ▽A = 0 ▽E = 0 ▽F = 0 ▼ = 0 ▽C = 0 ⊠ = 0 ■ = 0 ▽ = 0	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		DIMENSION UNITS MM		SCALE 10:1								
	GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± 3.0 °		DRWN BY JASANUMA		DATE 2015/12/01						1.0 FPC CONN ZIF (ST)		
	4 PLACES ± 0.2 3 PLACES ± 0.2 2 PLACES ± 0.2 1 PLACE ± 0.25 0 PLACES ± 0.3		CHK'D BY KTAKAHASHI		DATE 2015/12/08		PRODUCT CUSTOMER DRAWING						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPR BY YNOGAWA		DATE 2015/12/09						SERIES 52030		MATERIAL NUMBER SEE CHART
EC NO: 102046 DRWN: JASANUMA CHK'D: KTAKAHASHI APPR: YNOGAWA		A3		THIRD ANGLE PROJECTION		DOCUMENT NUMBER 520301000		DOC TYPE PSD		DOC PART 000		SHEET NUMBER 1 OF 2	



(仕上がり厚さ:0.3±0.05)
(THICKNESS:0.3±0.05)

適合FPC推奨寸法
APPLICABLE FPC RECOMMENDED DIM.



基板取付穴推奨寸法(t=1.6)
RECOMMENDED P.C.BOARD HOLE DIM.(t=1.6)
(マウント面)
(MOUNT SURFACE)

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補強フィルム材質は、ポリイミドを推奨致します。
接着剤は、熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THEROSETTING BONDING AGENT

QUALITY SYMBOLS ▽A = 0 ▽E = 0 ▽F = 0 ▼ = 0 ▽C = 0 ⊠ = 0 ■ = 0 ▽ = 0	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										
	EC NO: 102046 DRWN: JASANUMA CHK'D: KTAKAHASHI APPR: YNOGAWA	2015/12/01 2015/12/08 2015/12/09	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION UNITS	SCALE					
			ANGULAR TOL ± 3.0 °		MM	1:1					
			4 PLACES	± 0.2	DRWN BY	DATE	1.0 FPC CONN ZIF (ST)				
			3 PLACES	± 0.2	JASANUMA	2015/12/01					
			2 PLACES	± 0.2	CHK'D BY	DATE	PRODUCT CUSTOMER DRAWING				
	1 PLACE	± 0.25	KTAKAHASHI	2015/12/08							
	0 PLACES	± 0.3	APPR BY	DATE	SERIES: 52030 MATERIAL NUMBER: SEE CHART CUSTOMER: GENERAL						
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		YNOGAWA	2015/12/09							
			DRAWING SIZE	THIRD ANGLE PROJECTION	DOCUMENT NUMBER: 520301000 DOC TYPE: PSD DOC PART: 000 SHEET NUMBER: 2 OF 2						
		A3									